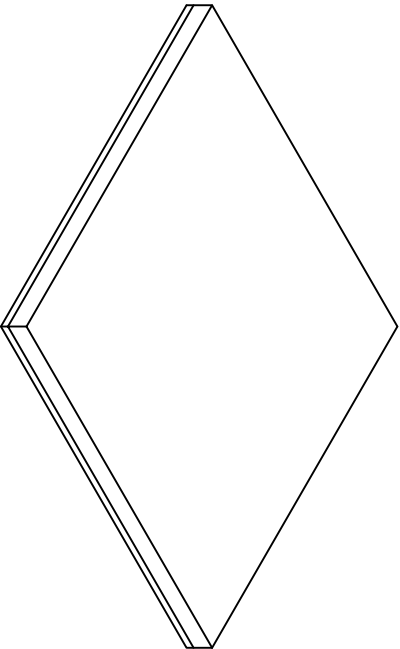


IMP0040174/001163001639000010-J4-01 IMP00126/001163001639170

REVISION HISTORY				
REV	ICH NUMBER	DESCRIPTION	ORIGINATOR	DATE
00	N/A	INITIAL RELEASE	JYRVU	02/26/07



7. REFERENCE SPECIFICATIONS:
A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
B. AAWW SPEC #001-0519-2062: MARKING.
6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 729.
3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 27 X 27.
2. THE BASIC SOLDER BALL GRID PITCH IS 0.50mm.
1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.
- NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN MILLIMETERS				THERMAL ANGLE PROTECTION			
DECIMAL				3:1			
X.XX ±0.1				APPROVALS			
X.XX ±0.05				DATE			
X.XX ±0.020				01/24/07			
INTERPRET DIM AND TOL PER				JYRVU			
ASME Y14.5M - 1994				01/24/07			
UNLESS OTHERWISE SPECIFIED				CHECKED			
N/A				JCYNA			
N/A				01/24/07			
N/A				PRODUCT MANAGER			
N/A				VPERE			
N/A				02/26/07			
N/A				RELEASED			
N/A				SINSEO			
DO NOT SCALE DRAWING				02/26/07			

Impkor Technology, Inc.
Chandler, Arizona, USA
Impkor Technology, Inc.
San Jose, California, USA
Impkor Technology Philippines, Inc.
Manila, Philippines



PACKAGE OUTLINE - MAF, 27 X 27 MATRIX,
14,00mm X 14,00mm X 0,80mm, 0,40mm MOLD CAP,
0,33mm BALL, 0,50mm PITCH, LAMINATE SUBSTRATE, AWW

SIZE	IMP NUMBER	IMP NUMBER	IMP NUMBER	REV
A3	N/A	N/A	339933	00
SHIP DIM TOLERANCE	N/A	PROD OUTLINE DIM TOL	NONE	SHEET 1 OF 3

FORM NO. IMP0040174-01

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